

WEST Search History

*Updated
Saved*

DATE: Thursday, March 11, 2004

<u>Hide?</u>	<u>Set</u>	<u>Name</u>	<u>Query</u>	<u>Hit Count</u>
<i>DB=USPT; PLUR=YES; OP=AND</i>				
<input type="checkbox"/>	L1		(semiconductor or semiconductor or semi-conductor or semi-conducter or computerchip or computer-chip or (computer near2 chip)).clm.	123905
<input type="checkbox"/>	L2		(etch\$ near3 (surface\$ or substract\$ or support\$ or solid\$)).clm.	7736
<input type="checkbox"/>	L3	L2 or l1		128592
<input type="checkbox"/>	L4	L3 and plasma\$.clm.		7300
<input type="checkbox"/>	L5	L4 and (heat\$ or temperatur\$).clm.		3059
<input type="checkbox"/>	L6	L5 and (method\$ or process\$).clm.		2922
<input type="checkbox"/>	L7	L6 and (gas\$ or helium\$).clm.		1673
<input type="checkbox"/>	L8	L7 and (conduct\$ or transfer\$ or remov\$).clm.		1081
<input type="checkbox"/>	L9	L8 and (space or area or compartment or containment).clm.		257
<input type="checkbox"/>	L10	L9 and (seal\$ or oring\$ or o-ring\$ or gasket\$ or gaskit\$ or block\$).clm.		24

END OF SEARCH HISTORY

[Generate Collection](#)[Print](#)**Search Results - Record(s) 1 through 24 of 24 returned.**

Γ 1. 6669783. 28 Jun 01; 30 Dec 03. High temperature electrostatic chuck. Sexton; Greg, et al. 118/728; 118/725 156/345.51 156/345.52 361/234. H01L021/306 C23C016/00.

Γ 2. 6653212. 09 Apr 01; 25 Nov 03. Method and apparatus for thin-film deposition, and method of manufacturing thin-film semiconductor device. Yamanaka; Hideo, et al. 438/485; 118/723VE 118/724 438/788 438/903. H01L021/20 C23C016/00.

Γ 3. 6379988. 16 May 00; 30 Apr 02. Pre-release plastic packaging of MEMS and IMEMS devices. Peterson; Kenneth A., et al. 438/51; 257/E21.502 257/E21.504 257/E23.124 257/E23.129 438/106 438/115 438/116 438/125 438/55 438/64. H01L021/00 H01L021/44 H01L021/48.

Γ 4. 6357385. 05 Oct 99; 19 Mar 02. Plasma device. Ohmi; Tadahiro, et al. 118/723AN; 118/723MW. C23C016/00.

Γ 5. 6352593. 11 Aug 97; 05 Mar 02. Mini-batch process chamber. Brors; Daniel L., et al. 118/724; 118/641 118/725 118/730. C23C016/48.

Γ 6. 6245202. 08 Oct 98; 12 Jun 01. Plasma treatment device. Edamura; Manabu, et al. 204/298.06; 118/723AN 118/723I 118/723IR 156/345.48 204/298.11 257/E21.218. C23C014/34.

Γ 7. 6245192. 30 Jun 99; 12 Jun 01. Gas distribution apparatus for semiconductor processing. Dhindsa; Rajinder, et al. 156/345.34; 438/706 438/712 438/729 438/730 438/731. C23F001/02.

Γ 8. 6234219. 25 May 99; 22 May 01. Liner for use in processing chamber. Donohoe; Kevin G.. 141/98; 118/715 118/723I 118/723R 118/723VE 141/11 141/63 141/65 141/66 141/69 141/85 141/91. B65B001/04 B65B003/04 B67C003/02.

Γ 9. 6217785. 09 Dec 96; 17 Apr 01. Scavenging fluorine in a planar inductively coupled plasma reactor. Collins; Kenneth S., et al. 216/68; 118/723I 156/345.48 438/723. H05H001/00 H01L021/00.

Γ 10. 6150232. 05 Feb 99; 21 Nov 00. Formation of low k dielectric. Chan; Lap, et al. 438/421; 257/522 257/E21.581 438/422. H01L021/76.

Γ 11. 6071372. 05 Jun 97; 06 Jun 00. RF plasma etch reactor with internal inductive coil antenna and electrically conductive chamber walls. Ye; Yan, et al. 156/345.48; 118/723I. C23F001/02 C23C016/00.

Γ 12. 5948704. 05 Jun 96; 07 Sep 99. High flow vacuum chamber including equipment modules such as a plasma generating source, vacuum pumping arrangement and/or cantilevered substrate support. Benjamin; Neil, et al. 438/715; 118/723R 118/725 118/728 118/733 156/345.51 216/67 216/68 216/69 279/128 427/569 427/570 427/571 427/573 427/575. H01L021/306 H01L021/3065 H05H001/00.

Γ 13. 5874014. 07 Jun 95; 23 Feb 99. Durable plasma treatment apparatus and method. Robson; Anthony E., et al. 216/68; 118/723E 118/723I 156/345.37 156/345.49 216/71 427/569 427/577. H05H001/00.

Γ 14. 5805408. 22 Dec 95; 08 Sep 98. Electrostatic clamp with lip seal for clamping substrates. Maraschin; Robert, et al. 361/234; H02N013/00.

Γ 15. 5720818. 26 Apr 96; 24 Feb 98. Conduits for flow of heat transfer fluid to the surface of an electrostatic chuck. Donde; Arik, et al. 118/500; 118/715 118/723E 118/725 118/728 156/345.53 29/428 29/458 29/592.1. C23C016/00.

Γ 16. RE34806. 04 May 92; 13 Dec 94. Magnetoplasmadynamic processor, applications thereof and methods. Cann; Gordon L.. 427/446; 118/723DC 118/723FI 156/345.39 204/156 216/67 219/121.43 219/121.47 422/186.03 422/186.05 422/186.21 427/571 427/580. C23C016/50.

Γ 17. 5370739. 15 Jun 92; 06 Dec 94. Rotating susceptor semiconductor wafer processing cluster tool module useful for tungsten CVD. Foster; Robert F., et al. 118/725; 118/720 118/727 118/728 118/729 118/730 118/733. C23C016/00.

Γ 18. 5262336. 13 Mar 92; 16 Nov 93. IGBT process to produce platinum lifetime control. Pike, Jr.; Douglas A., et al. 438/138; 257/133 257/139 257/142 257/156 257/E21.033 257/E21.218 257/E21.346 257/E21.385 257/E21.42 257/E29.013 257/E29.015 257/E29.066 257/E29.118 257/E29.2 257/E29.259 438/139 438/140. H01L021/00 H01L021/02 H01L021/467.

Γ 19. 5171393. 29 Jul 91; 15 Dec 92. Wafer processing apparatus. Moffat; William A.. 156/345.32; 216/67 216/91 216/92 257/E21.229. H01L021/306 B44C001/22.

Γ 20. 5087815. 30 Jul 90; 11 Feb 92. High resolution mass spectrometry of recoiled ions for isotopic and trace elemental analysis. Schultz; J. Albert, et al. 250/309; 250/287 250/307. H01J037/08.

Γ 21. 5009738. 01 Dec 89; 23 Apr 91. Apparatus for plasma etching. Gruenwald; Heinrich, et al. 156/345.47; 204/298.31 204/298.33 216/71. C23F001/02.

Γ 22. 4682564. 11 Jul 83; 28 Jul 87. Magnetoplasmadynamic processor, applications thereof and methods. Cann; Gordon L.. 118/620; 118/50.1 118/721 118/723DC 118/729. B05B005/02.

Γ 23. 4483737. 31 Jan 83; 20 Nov 84. Method and apparatus for plasma etching a substrate. Mantei; Thomas D.. 438/732; 156/345.46 204/192.32 204/298.34 204/298.37. H01L021/306 B44C001/22 C03C015/00 C03C025/06.

Γ 24. 3908183. 14 Mar 73; 23 Sep 75. Combined ion implantation and kinetic transport deposition process. Ennis, Jr.; Robert M.. 257/734; 148/DIG.169 148/DIG.20 148/DIG.45 204/298.05 250/492.3 257/E21.333 257/E21.334 427/458 427/523 427/551 427/573 438/530 438/533 438/913. B05C005/00 B44D001/18 B05B005/00 B01J017/00.

Terms	Documents
L9 and (seal\$ or oring\$ or o-ring\$ or gasket\$ or gasket\$ or block\$).clm.	24

[Prev Page](#) [Next Page](#) [Go to Doc#](#)

First Hit Fwd Refs

L10: Entry 1 of 24

File: USPT

Dec 30, 2003

US-PAT-NO: 6669783

DOCUMENT-IDENTIFIER: US 6669783 B2

TITLE: High temperature electrostatic chuck

DATE-ISSUED: December 30, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Sexton; Greg	Fremont	CA		
Schoepp; Alan	Ben Lomond	CA		
Kennard; Mark Allen	Pleasanton	CA		

ASSIGNEE-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY	TYPE CODE
Lam Research Corporation	Fremont	CA			02

APPL-NO: 09/ 892458 [PALM]

DATE FILED: June 28, 2001

INT-CL: [07] H01 L 21/306, C23 C 16/00

US-CL-ISSUED: 118/728; 361/234, 156/345.51, 156/345.52, 118/725

US-CL-CURRENT: 118/728; 118/725, 156/345.51, 156/345.52, 361/234

FIELD-OF-SEARCH: 361/234, 156/345.53, 118/728, 118/725

PRIOR-ART-DISCLOSED:

U.S. PATENT DOCUMENTS

PAT-NO	ISSUE-DATE	PATENTEE-NAME	US-CL
<input type="checkbox"/> 4340462	July 1982	Koch	
<input type="checkbox"/> 4534816	August 1985	Chen et al.	
<input type="checkbox"/> 4579618	April 1986	Celestino et al.	
<input type="checkbox"/> 4615755	October 1986	Tracy et al.	
<input type="checkbox"/> 4665463	May 1987	Ward et al.	
<input type="checkbox"/> 4692836	September 1987	Suzuki	
<input type="checkbox"/> 4948458	August 1990	Ogle	
<input type="checkbox"/> 5055964	October 1991	Logan et al.	